

Study of Drain Characteristics of N-Channel MOSFET with Varying Impurity Concentration - A Comparative Study

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Abstract: In this work, *n*-channel MOSFETs of varying Boron doping profiles, using Silvaco TCAD tools namely Athena and Atlas, have been analysed. The fabrication of *n*MOS has been done through a series of fabrication steps, which include wafer selection with appropriate orientation and phosphorus doping, oxide diffusion, boron-implantation for *p*-well formation, polysilicon deposition, phosphorus-implantation for heavily doped *n*⁺ regions, aluminium-deposition for source/drain contact and extraction of unused materials. All of these steps have been performed through the Athena tool. Afterward, Atlas performs several simulations to deduce the transfer characteristics curves (the I_D - V_{GS} curves). Performance parameters of MOSFETs of varying doping profiles, such as Threshold Voltage (V_{TH}), Transconductance, and channel length modulation have been compared. These simulation-based analyses provide a better understanding of an *n*MOS device's fabrication process and a clearer physical insight into its characteristic curves and performance parameters.

Keywords: Doping, Threshold Voltage, transconductance, channel length modulation

